

Session VII

Reliability and Diagnostics

Chairman:

Z. Bardai
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Motorola

This session addresses the reliability concerns that need to be satisfied for broader application of GaAs based devices and MMICs. Flip chip techniques for novel packaging concepts are addressed. A novel RF probe for circuit diagnostics of MMICs is described. These tools and data will help launch MMIC technology into high volume manufacturing.

3:30 p.m.-5:10 p.m., Monday, May 15, 1995
Room CC-A1